

SolidMatrix® Surface Mount Fuses

FA Series (Fast Acting), 1206 Size



Features:

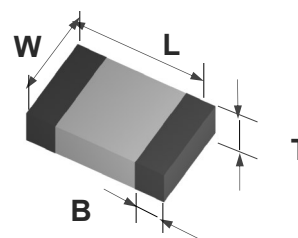
- Multilayer monolithic structure with glass ceramic body and silver fusing element
- Silver termination with nickel and pure-tin solder plating, providing excellent solderability
- Compatible with both wave and reflow soldering processes
- Operating temperature range: -55°C to +150°C (with de-rating)

Clearing Time Characteristics:

% of current rating	Clearing time at 25°C
100%	4 hours min.
250%	5 seconds max.
400%	0.05 seconds max.

Shape and Dimensions:

Unit	Inch	mm
L	0.126 ± 0.008	3.20 ± 0.20
W	0.063 ± 0.008	1.60 ± 0.20
T	0.043 ± 0.008	1.10 ± 0.20
B	0.020 ± 0.010	0.51 ± 0.25



Agency Approval:

Recognized Under the Components Program of UL.
File Number: E232989.

Patents:

Patent numbers "US6,602,766", "US7,268,661 B2", "ZL02114719.1", "ZL200410104280.7", "ZL201020551360.8", "ZL201010299185.2", "ZL201220030614.0", "ZL201210020693.1".

Ordering Information:

Part Number	Current Rating (A)	Voltage Rating (VDC)	Interrupting Ratings	Nominal Cold DCR (Ω) ¹	Nominal I^2t (A ² s) ²	Marking Code ³
F1206FA0500V063TM	0.5	63	50 A at rated voltages	0.730	0.002	C
F1206FA0750V063TM	0.75	63		0.513	0.005	D
F1206FA1000V063TM	1.0	63		0.220	0.011	E
F1206FA1500V063TM	1.5	63		0.120	0.024	G
F1206FA1750V063TM	1.75	63		0.100	0.045	H
F1206FA2000V063TM	2.0	63		0.050	0.075	I
F1206FA2500V032TM	2.5	32		0.035	0.11	J
F1206FA3000V032TM	3.0	32	45 A at rated voltages	0.031	0.21	K
F1206FA4000V032TM	4.0	32		0.022	0.35	M
F1206FA5000V032TM	5.0	32		0.015	0.60	N
F1206FA6000V032TM	6.0	32		0.013	1.0	+
F1206FA7000V032TM	7.0	32		0.011	1.6	-
F1206FA8000V032TM	8.0	32		0.008	2.3	=

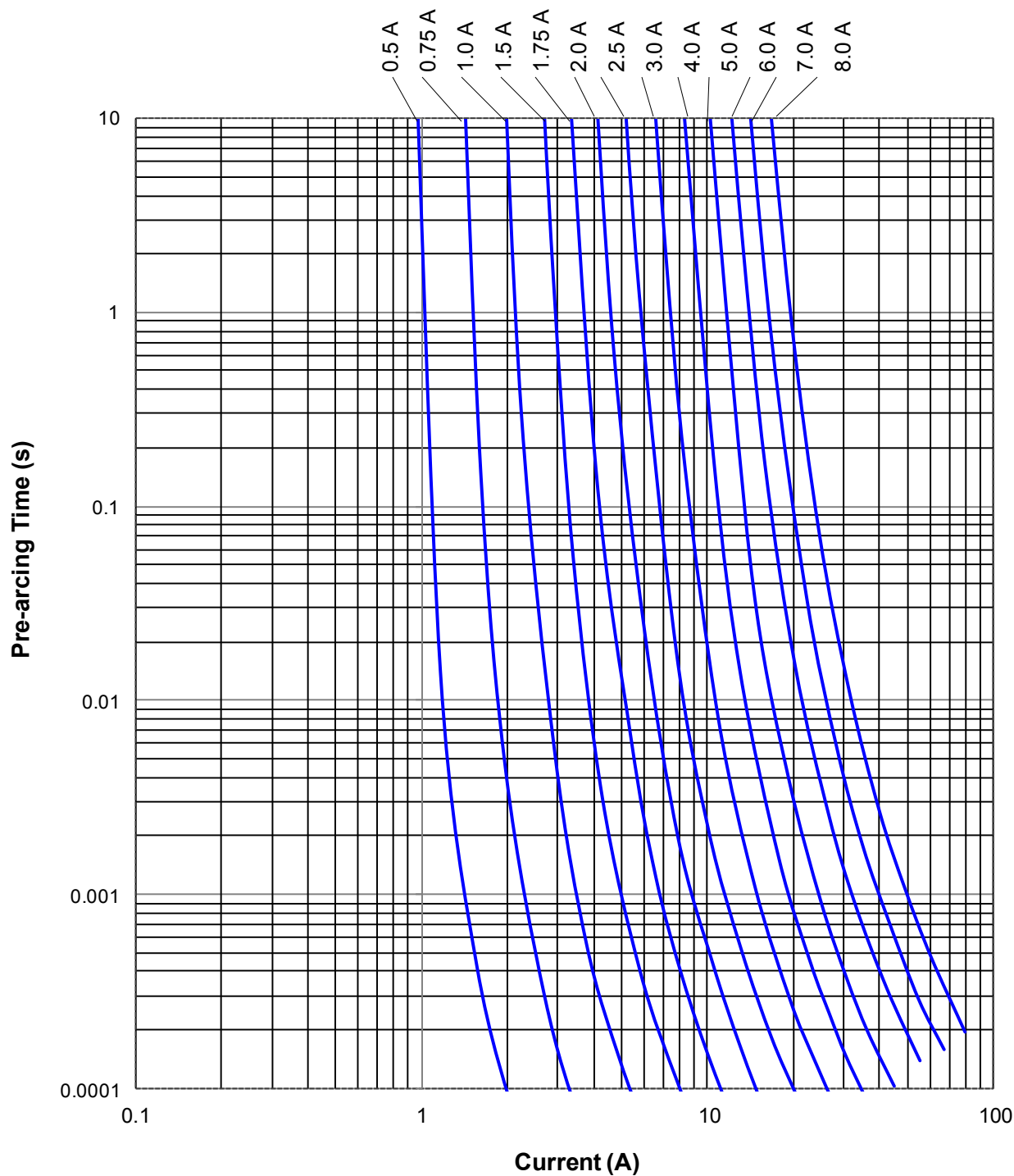
1. Measured at ≤ 10% rated current and 25°C ambient.

2. Melting I^2t at 0.001 second pre-arcing time.

3. Black Marking Character Code.

SolidMatrix[®] Surface Mount Fuses FA Series (Fast Acting), 1206 Size

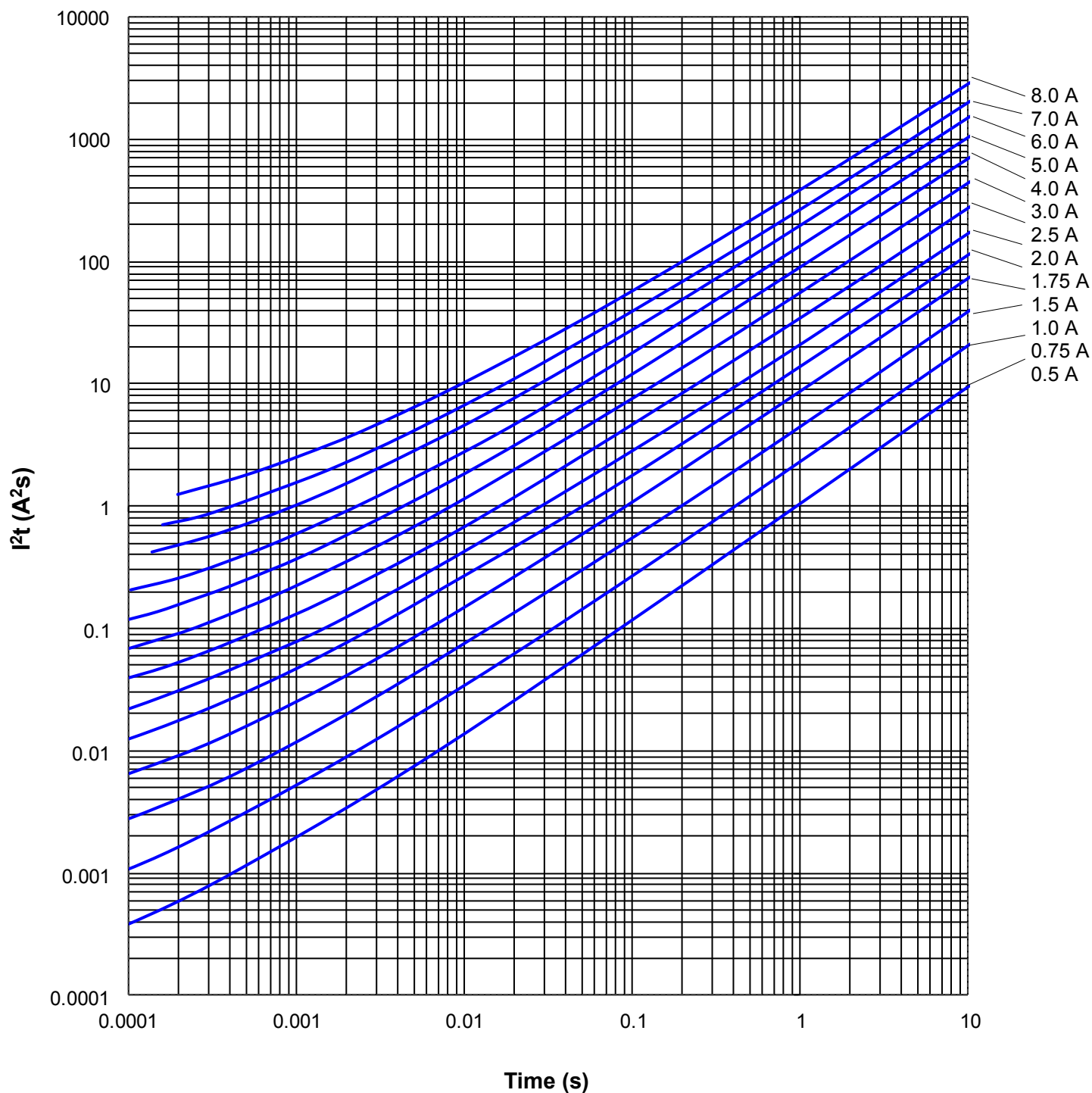
Average Pre-arcing Time Curves:



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Average I^2t vs. t Curves:



SolidMatrix® Surface Mount Fuses

Product Identification:

F 0603 FA 1000 V032 T M

(1) (2) (3) (4) (5) (6) (7)

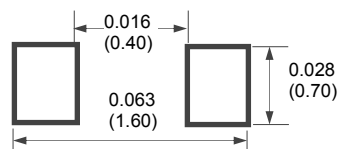
- (1) **Product Code:** F—Chip Fuse
- (2) **Size Code:** Standard EIA Chip Sizes
- (3) **Series Code:** FA - Fast Acting, SB - Slow Blow, HI - High Inrush, FF - Very Fast Acting, HB - High Current
- (4) **Current Rating Code:** 1000 - 1000 mA (For HB, 10 - 10A)
- (5) **Voltage Rating Code:** V032 - 32 VDC
- (6) **Package Code:** T - Tape & Reel, B - Bulk
- (7) **Marking Code:** M - With Marking

F 1206 HC 20A0 T M

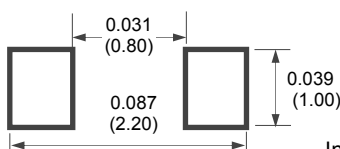
(1) (2) (3) (4) (5) (6)

- (1) **Product Code:** F—Chip Fuse
- (2) **Size Code:** L x W (inch),
the first two digits-L (length),
the last two digits-W (width)
- (3) **Series Code:** HC Series
- (4) **Current Rating Code:** 20A0—20.0A
- (5) **Package Code:** T - Tape & Reel, B - Bulk

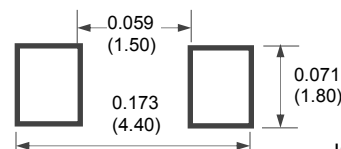
Recommended Land Pattern:



0402 Size



0603 Size



1206 Size

Environmental Tests:

No.	Test	Requirement	Test condition	Test reference
1	Soldering heat resistance	DCR change $\leq \pm 10\%$ No mechanical damage	One dip at 260°C for 60 seconds	MIL-STD-202 Method 210
2	Solderability	Minimum 95% coverage	One dip at 245°C for 5 seconds	MIL-STD-202 Method 208
3	Thermal shock	DCR change $\leq \pm 10\%$ No mechanical damage	100 cycles between -65°C and +125°C	MIL-STD-202 Method 107
4	Moisture resistance	DCR change $\leq \pm 15\%$ No excessive corrosion	10 cycles	MIL-STD-202 Method 106
5	Salt spray	DCR change $\leq \pm 10\%$ No excessive corrosion	48 hour exposure	MIL-STD-202 Method 101
6	Mechanical vibration	DCR change $\leq \pm 10\%$ No mechanical damage	0.4 " D.A. or 30 G between 5 – 3000 Hz	MIL-STD-202 Method 204
7	Mechanical shock	DCR change $\leq \pm 10\%$ No mechanical damage	1500 G, 0.5 ms, half-sine shocks	MIL-STD-202 Method 213
8	Life	No electrical "opens" during testing voltage drop change shall be less than $\pm 20\%$ of initial value	80% rated current (75% for < 1 A fuses) for 2000 hours at ambient temperature between +20°C and +30°C	Refer to AEM QIQ106

SolidMatrix® Surface Mount Fuses

Electrical Specification:

Clearing Time Characteristics:

Same as specified on the Short Form Data Sheet

Insulation Resistance after Opening:

20,000 ohms typical when cleared with rated voltage applied. Fuse clearing under low voltage conditions may result in lower after clearing insulation resistance values. (Note: Under normal fault conditions (low or rated voltage conditions), AEM SolidMatrix fuses provide sufficient after clearing insulation resistance values for circuit protection.)

Current Carrying Capacity:

100% rated current at +25°C ambient for 4 hours minimum when evaluated per MIL-PRF-23419

Interrupt Ratings:

Fuse Selection and Temperature De-rating Guideline:

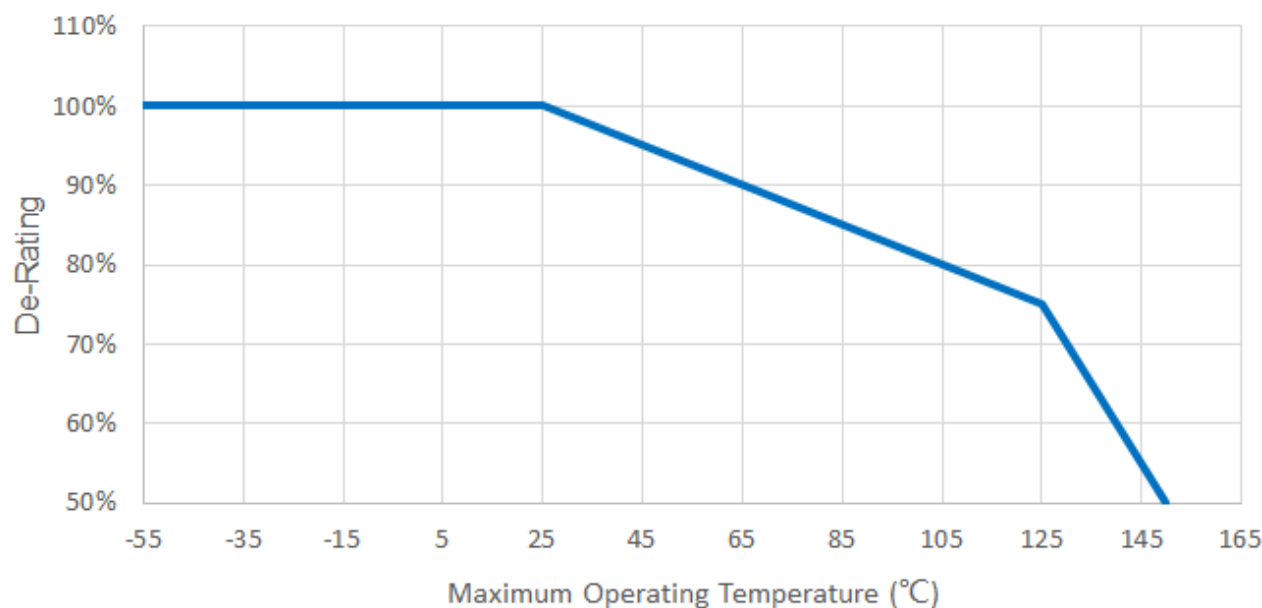
The ambient temperature affects the current carrying capacity of fuses. When a fuse is operating at a temperature higher than 25°C, the fuse shall be “de-rated”.

To select a fuse from the catalog, the following rule may be followed:

Catalog Fuse Current Rating = Nominal Operating Current / 0.75 / % De-rating at the maximum operating temperature.

Example: At maximum operating temperature of 65°C, % De-rating is 90%. The nominal operating current is 4 A. The current rating for fuse selected from the catalog shall be: $4 / 0.75 / 90\% = 5.9$ or 6 A. Specifications and descriptions in this literature are as accurate as known at the time of publish, but are subject to change without notice.

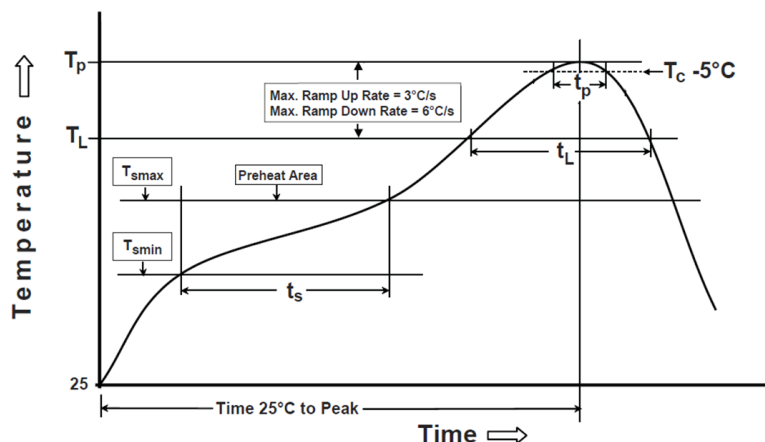
Temperature De-Rating Curve for SolidMatrix Fuses



SolidMatrix® Surface Mount Fuses

Soldering Temperature Profile:

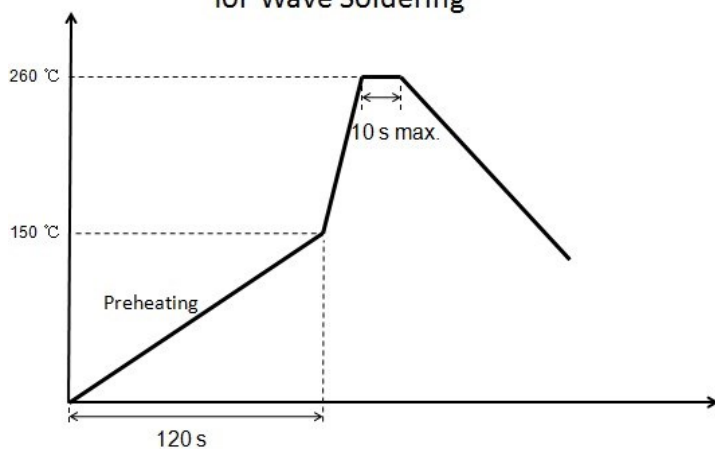
* Recommended Temperature Profile for Reflow Soldering



Profile Feature	Pb-Free Assembly
Preheat/Soak Temperature Min (T_{smin}) Temperature Max (T_{smax}) Time (t_s) from (T_{smin} to T_{smax})	150°C 200°C 60~120 seconds
Ramp-up rate (T_L to T_p)	3°C/second max.
Liquidous temperature (T_L) Time (t_L) maintained above T_L	217°C 60~150 seconds
Peak package body temperature (T_p)	260°C
Time (t_p)*within 5°C of the specified classification temperature (T_c)	30 seconds *
Ramp-down rate (T_p to T_L)	6°C/second max.
Time 25°C to peak temperature	8 minutes max.
* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum	

* Recommended Temperature Profile for Wave Soldering

Recommended Temperature Profile for Wave Soldering



Notice: Wave Soldering is suitable for 1206 and 0603 size.

Packaging:

Chip Size	Parts on 7 inch (178 mm) Reel
0402 (1005)	10,000
0603 (1608)	4,000
0603FF (1608)	6,000
1206 (3216)	3,000

Disclaimer

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